

Notes:

1. Material:

Contact: High Performance Copper Alloy  
 Shielding Cover: High Performance Copper Alloy  
 Housing: High Temperature Theroplastic.

2. Finish:

Contact: 50u" Nickel Underplating Overall. Gold Flash(2~3u") on Contact Area & Solder tail.  
 Shielding Cover: 50u" Nickel Underplating Overall. Gold Plating See Order Information.

△ 3. Halogen-Free Product P/N:  
 C90P103-0X00X-H

Shielding Cover Plating:

- 4: Gold Flash on contact area & solder tail.
- 5: Nickel plated on contact area. Gold flash on solder tail.

Package:

- 0: Carrier Tape W=8mm, Pitch=4mm. (PKG. SPEC. AAA-C90-0301)
- 1: Carrier Tape W=12mm, Pitch=8mm. (PKG. SPEC. AAA-C90-0302)
- 2: Antistatic Type

說明:

1. 材料:

訊號端子: 高性能銅合金  
 鐵殼: 高性能銅合金  
 塑膠: 高溫熱塑性塑膠

2. 電鍍:

訊號端子: 50u" 鎳底, 接觸區域與焊錫區域刷金(2~3u")  
 鐵殼: 50u" 鎳底, 接觸區域與焊錫區域依訂單需求選擇電鍍方式.

△ 3. 無鹵料號:

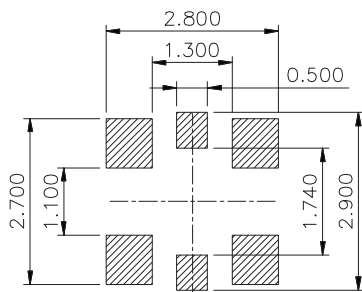
C90P103-0X00X-H

鐵殼電鍍:

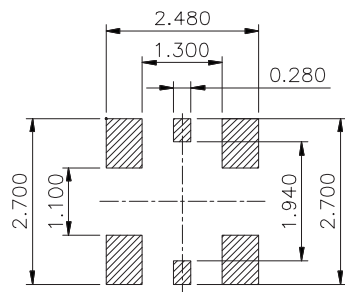
- 4: 接觸區域與焊錫區域鍍金.
- 5: 接觸區域鍍鎳, 焊錫區域鍍金.

包裝:

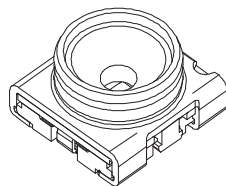
- 0: 載帶 寬度=8mm, Pitch=4mm. (包裝規範 AAA-C90-0301)
- 1: 載帶 寬度=12mm, Pitch=8mm. (包裝規範 AAA-C90-0302)
- 2: 抗靜電規格



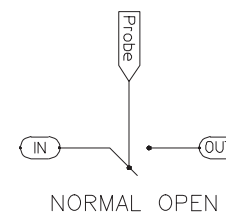
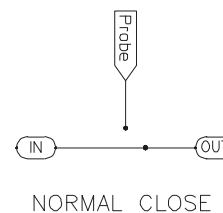
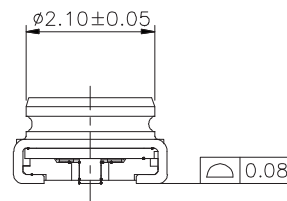
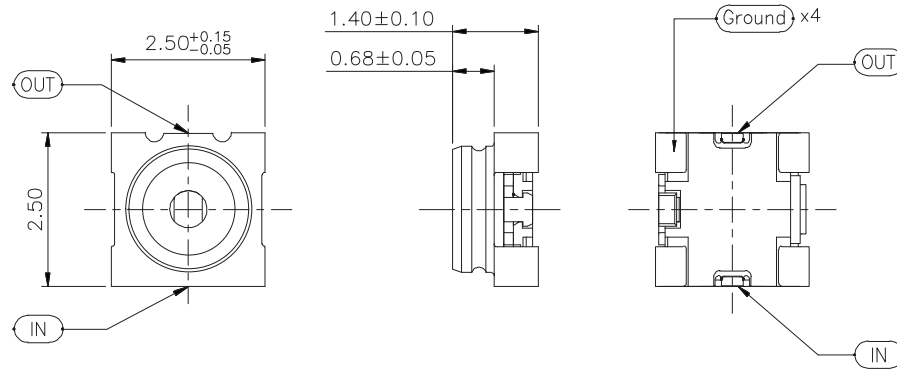
Recomand PCB Layout



Recomand Stencil Mask Pattern  
 (Mask Thickness 0.08mm)



DCC ISSUE	Speedtech		REV	MODIFICATION	DATE	DRAW	APPROVE
	2014.08.12		L	EN1303038	12-MAR-13	DANIEL	C.Y
	DCC 發行		M	EN1308046	21-AUG-13	DANIEL	C.Y
			N	EN1408015	06-AUG-14	JAMES	Y.J



DIMENSION IN mm [Inch]		PROD. SPEC.	深圳市华灿天禄电子有限公司	
TOLERANCE UNLESS OTHERWISE SPECIFIED			FILE NO.	DWG NO.
.X±0.25	X.°± 5°	PKG. SPEC.		HC-RF-C90-103
.XX±0.10	.X°±3°		TITLE RF Switch Connector	
.XXX±0.06	.XX°±		CUSTOMER DRAWING	
APPROVE	CHECK	DRAW	PROJ.	SHEET 1 / 1
Y.J	T.C	JAMES	SCALE 8:1	SIZE A4
			REV N	